

Material Content Data Sheet

Sales Product Name	AIM12S112EB1	**Issued**	09. July 2025
MA#	MA006140631		
Package	PG-MDIP-24-64	**Weight:**	7143.25 mg

Construction Element	Material group	Materials	CAS if applicable	Weight [mg]	Average mass [%]	Sum [%]	Average mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	7.056	0.10	0.10	988	988
chip_2	inorganic material	siliconcarbide	409-21-2	1.354	0.02	0.02	189	189
chip_3	inorganic material	siliconcarbide	409-21-2	1.354	0.02	0.02	189	189
chip_4	inorganic material	siliconcarbide	409-21-2	1.354	0.02	0.02	189	189
chip_5	inorganic material	siliconcarbide	409-21-2	1.354	0.02	0.02	189	189
chip_6	inorganic material	siliconcarbide	409-21-2	1.354	0.02	0.02	189	189
chip_7	inorganic material	siliconcarbide	409-21-2	1.354	0.02	0.02	189	189
leadframe	inorganic material	phosphorus	7723-14-0	0.383	0.01		54	
	non noble metal	iron	7439-89-6	1.276	0.02		179	
	non noble metal	copper	7440-50-8	1274.200	17.84	17.87	178379	178612
wire	noble metal	gold	7440-57-5	0.609	0.01		85	
	non noble metal	aluminium	7429-90-5	29.085	0.41	0.42	4072	4157
encapsulation	organic material	carbon black	1333-86-4	30.588	0.43		4282	
	plastics	epoxy resin	-	382.346	5.35		53526	
	inorganic material	silicondioxide	60676-86-0	3410.525	47.72	53.50	477447	535255
leadfinish	non noble metal	tin	7440-31-5	41.241	0.58	0.58	5773	5773
plating	non noble metal	nickel	7440-02-0	5.991	0.08	0.08	839	839
solder	non noble metal	antimony	7440-36-0	0.401	0.01		56	
	noble metal	silver	7440-22-4	1.002	0.01		140	
	non noble metal	tin	7440-31-5	2.604	0.04	0.06	365	561
glue	organic material	ethene, 1,1,2,2-tetrafluoro-	925918-64-5	0.004			1	
	plastics	acrylic resin	-	0.145			20	
	plastics	maleimide resin	-	0.146			20	
	inorganic material	silicondioxide	60676-86-0	0.152			21	
	plastics	epoxy resin	-	0.224			31	
	noble metal	silver	7440-22-4	0.438	0.01	0.01	61	154
smd	inorganic material	silicondioxide	60676-86-0	0.002			1	
	noble metal	gold	7440-57-5	0.008			1	
	noble metal	palladium	7440-05-3	0.013			2	
	organic material	ethyl cellulose	9004-57-3	0.016			2	
	noble metal	silver	7440-22-4	0.021			3	
	organic material	DEGBE	112-34-5	0.071			10	
	inorganic material	cobalt(II)oxide	1307-96-6	0.136			19	

	inorganic material	copperoxide	1317-38-0	0.390	0.01		55	
	inorganic material	manganesedioxide	1313-13-9	0.446	0.01	0.02	62	155
pcb metal	non noble metal	copper	7440-50-8	13.571	0.19	0.19	1900	1900
pcb plastic	miscellaneous	miscellaneous	-	26.373	0.37		3692	
	inorganic material	silicondioxide	60676-86-0	42.196	0.59		5907	
	organic material	Poly[phenylglycidylether-coformaldehyde]	28064-14-4	50.108	0.70		7015	
	inorganic material	glass fibre	-	145.050	2.03	3.69	20306	36920
pcb plating	noble metal	gold	7440-57-5	0.042			6	
	non noble metal	nickel	7440-02-0	1.898	0.03	0.03	266	272
dcb ceramic	inorganic material	zirconium dioxide	1314-23-4	5.122	0.07		717	
	inorganic material	aluminum nitride	24304-00-5	454.293	6.36	6.43	63598	64315
dcb metal	non noble metal	copper	7440-50-8	1206.956	16.90	16.90	168965	168965
deviation	< 10%				Sum in total:	100.00		1000000

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